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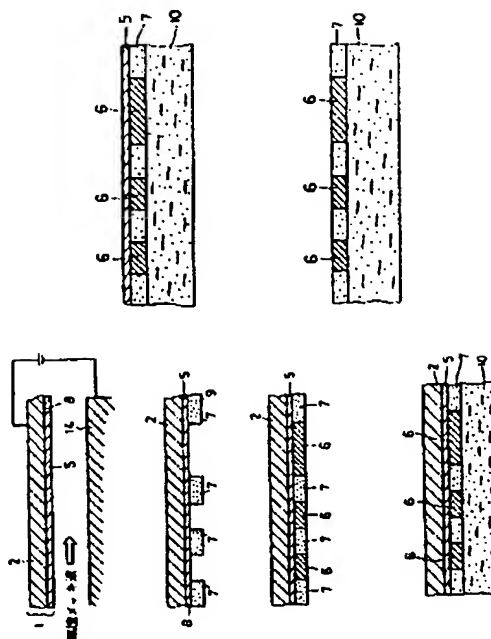
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APPLICANT : MEIKO DENSHI KOGYO KK;

INVENTOR : KANDA TAKESHI;

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TITLE : MANUFACTURE OF CONDUCTOR
CIRCUIT BOARD



ABSTRACT : PURPOSE: To form a conductor circuit whose transcription performance is good, whose production yield is high and whose density is high by a method wherein, after a copper-plated layer and a copper circuit have been formed on a flat conductive base material under a specific condition, a transcription and deposition operation onto an insulating base material is executed by using a heating and pressure-bonding process.

CONSTITUTION: The surface of a flat conductive base material 2 is polished at a roughness of a range of 0.28~0.23 μm and this material is used as a cathode 1; this cathode is situated face to face with an anode 14 at a prescribed separation distance of 3~30 mm; a copper-plated layer 5 is electrolyzed and precipitated on the conductive base material 2 by using a so-called high-speed plating method. A resist mask 7 is formed on the surface of the copper-plated layer 5 excluding a part where conductor circuits 6 are formed. After that, at least one layer of a metal-plated layer is formed under a different etching condition; the conductor circuits 6 are formed. The conductor circuits 6 formed on the conductive base material 2 is deposited on an insulating base material 10 together with the copper-plated layer 5 and the conductive base material 2 via an adhesive agent; these are pressed and united. The conductor circuits 6, the resist mask 7 and the copper-plated layer 5 are transcribed onto the insulating base material 10. The copper-plated layer 5 is removed by etching; the circuit board is completed.

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